# 2SB0621 (2SB621), 2SB0621A (2SB621A)

## Silicon PNP epitaxial planar type

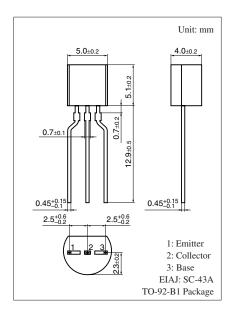
For low-frequency driver amplification Complementary to 2SD0592 (2SD592), 2SD0592A (2SD592A)

#### ■ Features

- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE}(\text{sat})}$
- High transition frequency f<sub>T</sub>

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SB0621	$V_{CBO}$	-30	V
(Emitter open)	2SB0621A		-60	
Collector-emitter voltage	2SB0621	V <sub>CEO</sub>	-25	V
(Base open)	2SB0621A		-50	
Emitter-base voltage (Coll	V <sub>EBO</sub>	-5	V	
Collector current	$I_{C}$	-1	A	
Peak collector current	$I_{CP}$	-1.5	A	
Collector power dissipation	P <sub>C</sub>	750	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

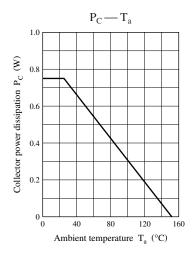
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage	2SB0621	V <sub>CBO</sub>	$I_C = -10 \mu A, I_E = 0$	-30			V
(Emitter open)	2SB0621A			-60			
Collector-emitter voltage	2SB0621	V <sub>CEO</sub>	$I_C = -2 \text{ mA}, I_B = 0$	-25			V
(Base open)	2SB0621A			-50			
Emitter-base voltage (Collector open)		V <sub>EBO</sub>	$I_E = -10 \ \mu A, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)		$I_{CBO}$	$V_{CB} = -20 \text{ V}, I_E = 0$			- 0.1	μΑ
Forward current transfer ratio		h <sub>FE1</sub> *	$V_{CE} = -10 \text{ V}, I_{C} = -500 \text{ mA}$	85		340	_
		h <sub>FE2</sub>	$V_{CE} = -5 \text{ V}, I_{C} = -1 \text{ A}$	50			_
Collector-emitter saturation voltage		V <sub>CE(sat)</sub>	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		- 0.2	- 0.4	V
Base-emitter saturation voltage		V <sub>BE(sat)</sub>	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		- 0.85	-1.2	V
Transition frequency		$f_T$	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance (Common base, input open circuited)		C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		20	30	pF

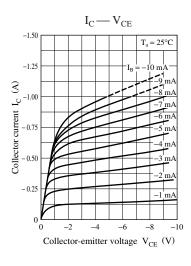
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

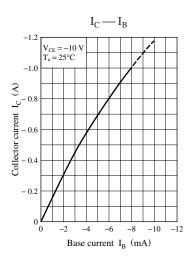
#### 2. \*: Rank classification

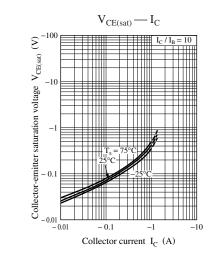
Rank	Q	R	S	
$h_{\rm FE1}$	85 to 170	120 to 240	170 to 340	

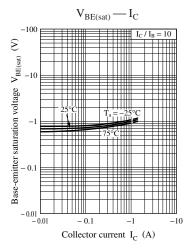
Note) The part numbers in the parenthesis show conventional part number.

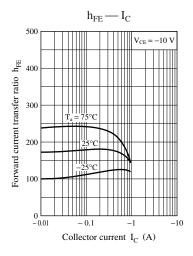


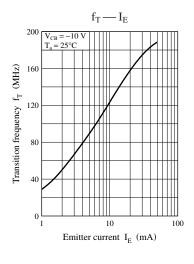


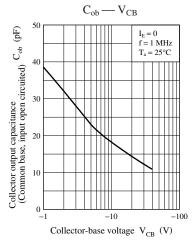


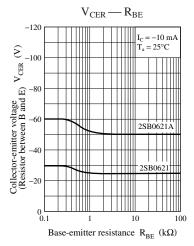


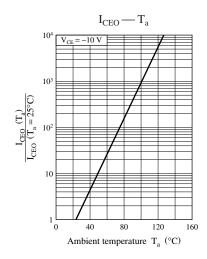


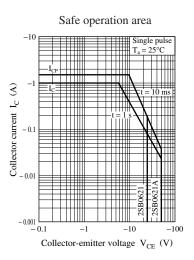












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